

2707482

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DIN rail housing, Lower housing part with metal foot catch, tall design, with vents, width: 22.6 mm, height: 99 mm, depth: 107.3 mm, color: light grey (similar RAL 7035), cross connection: integrated bus connector, number of positions cross connector: 10, Bus connector: 10 parallel contacts

Your advantages

- · Tool-free mounting
- · Available in overall widths from 12.5 mm to 90 mm, modular extension possible
- · Flammability rating V0 in accordance with UL 94
- · Variety of connection technology
- · Can be mounted on the DIN rail
- With integrated or DIN-rail-mountable bus connector as an option

Commercial data

Item number	2707482
Packing unit	10 pc
Minimum order quantity	10 pc
Note	Made to order (non-returnable)
Sales key	AC08
Product key	ACHAAB
GTIN	4017918900595
Weight per piece (including packing)	55.47 g
Weight per piece (excluding packing)	41.518 g
Customs tariff number	85369010
Country of origin	DE

2707482

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Technical data

Notes

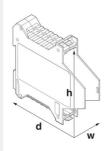
General	Refer to the data sheet for the range in the download area.
General	Material of contact pads for bus connector, galvanic gold (hard gold)

Product properties

Туре	Lower housing parts with vents, housing cover necessary to complete the module
Product type	Enclosure bottom part
Housing series	ME
Product family	MEUT BUS/10
Туре	Lower housing part with metal foot catch, tall design
Housing type	DIN rail housing
Ventilation openings present	yes

Dimensions

Dimensional drawing



Width	22.6 mm
Height	99 mm
Depth	107.3 mm
Depth from top edge of DIN rail	100.7 mm
Depth from top edge of DIN rail to support point on upper part	68.5 mm

PCB design

Material specifications

Color (Housing)	light grey (RAL 7035)
Flammability rating according to UL 94	VO
CTI according to IEC 60112	600
Surface characteristics	untreated
Housing material	Polyamide

Environmental and real-life conditions

Power dissipation single housing for 20 $^\circ\text{C}$





2707482

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Ambient temperature	20 °C
Reduction factor	1
Mounting position	vertical
Power dissipation	6.1 W
Power dissipation single housing for 30 $^\circ ext{C}$	
Ambient temperature	30 °C
Reduction factor	0.91
Mounting position	vertical
Power dissipation	5.5 W
Power dissipation single housing for 40 °C	
Ambient temperature	40 °C
Reduction factor	0.81
Mounting position	vertical
Power dissipation	4.9 W
Power dissipation single housing for 50 °C	
Ambient temperature	50 °C
Reduction factor	0.7
Mounting position	vertical
Power dissipation	4.3 W
Power dissipation single housing for 60 °C	
Ambient temperature	60 °C
Reduction factor	0.57
Mounting position	vertical
Power dissipation	3.5 W
Power dissipation single housing for 70 °C	
Ambient temperature	70 °C
Reduction factor	0.49
Mounting position	vertical
Power dissipation	3.1 W
Vibration test	
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Acceleration	2g (58.1 Hz 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis
Glow-wire test	
Specification	IEC 60695-2-11:2014-02
Temperature	850 °C



2707482

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	30 s
Time of exposure	
hermal stability / ball thrust test	
Specification	IEC 60695-10-2:2014-02
Temperature	125 °C
Test duration	1 h
Force	20 N
echanical strength / tumbling barrel	
Specification	IEC 60998-1:2002-12
Height of fall	50 cm
Frequency	10
hocks	
Specification	IEC 60068-2-27:2008-02
Pulse shape	Half-sine
Acceleration	15g
Shock duration	11 ms
Number of shocks per direction	3
Test directions	X-, Y- and Z-axis (pos. and neg.)
egree of protection (IP code) Specification	
Specification mbient conditions	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0
Specification mbient conditions Max. IP code to attain	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0
Specification mbient conditions Max. IP code to attain Ambient temperature (operation)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation)
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 %
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % 1
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % 1 Insertion (optional latching by PCB stop)
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) Cataa Number of PCB holders Type of PCB mount Thickness of the PCB	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % 1
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % 1 Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm DIN rail mounting
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % 1 Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm
Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm DIN rail mounting
Specification Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB Junting Mounting type Mounting position	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 % Insertion (optional latching by PCB stop) 1.4 mm 1.8 mm DIN rail mounting



2707482

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Classifications

ECLASS

	ECLASS-11.0	27182702
	ECLASS-13.0	27190601
E٦	IM	
	ETIM 9.0	EC001031
U	NSPSC	
	UNSPSC 21.0	31261500

2707482

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Environmental product compliance

China RoHS	Environmentally friendly use period: unlimited = EFUP-e
	No hazardous substances above threshold values

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